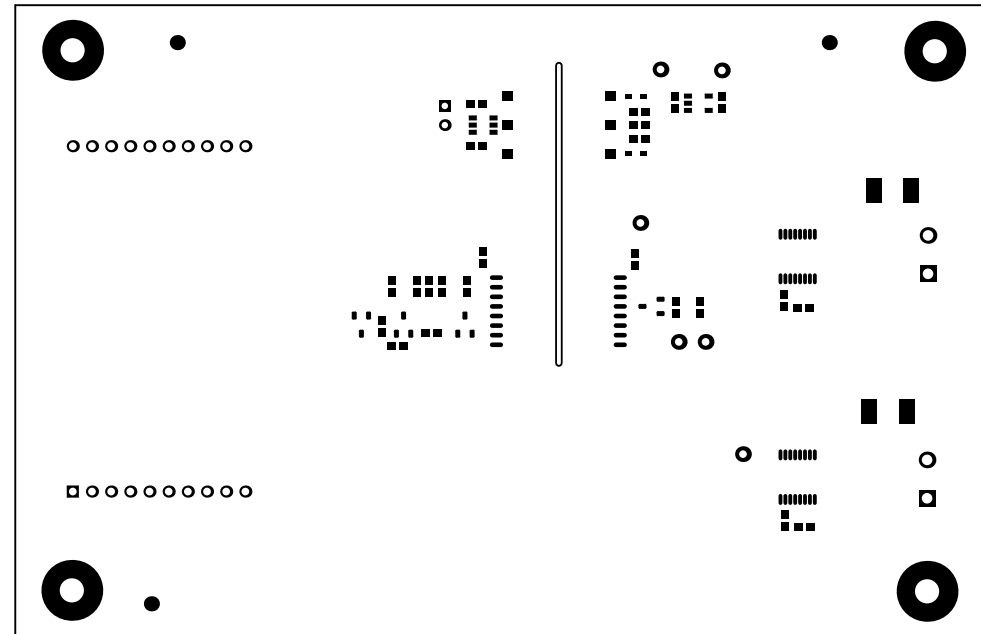
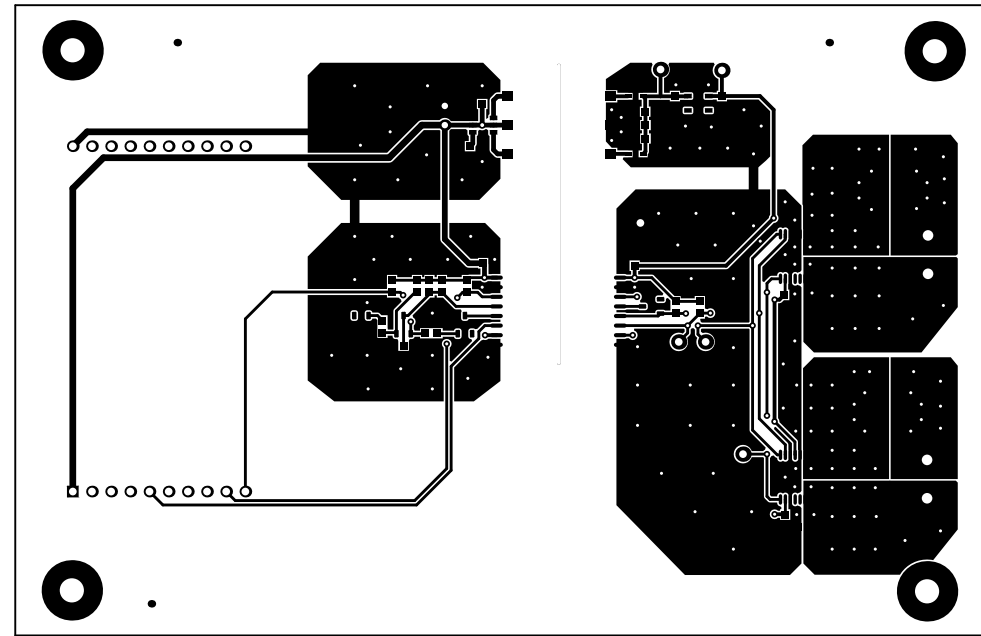


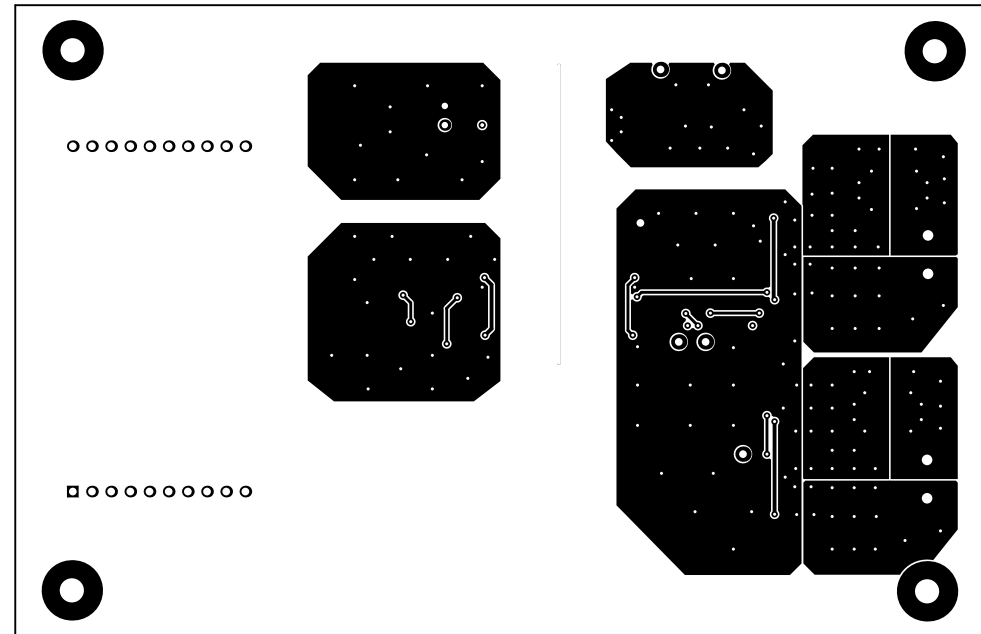
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01590	REV: R1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-01590		
PLOT NAME = Top Overlay	GENERATED : 10/2/2017 2:27:04 PM	TEXAS INSTRUMENTS	



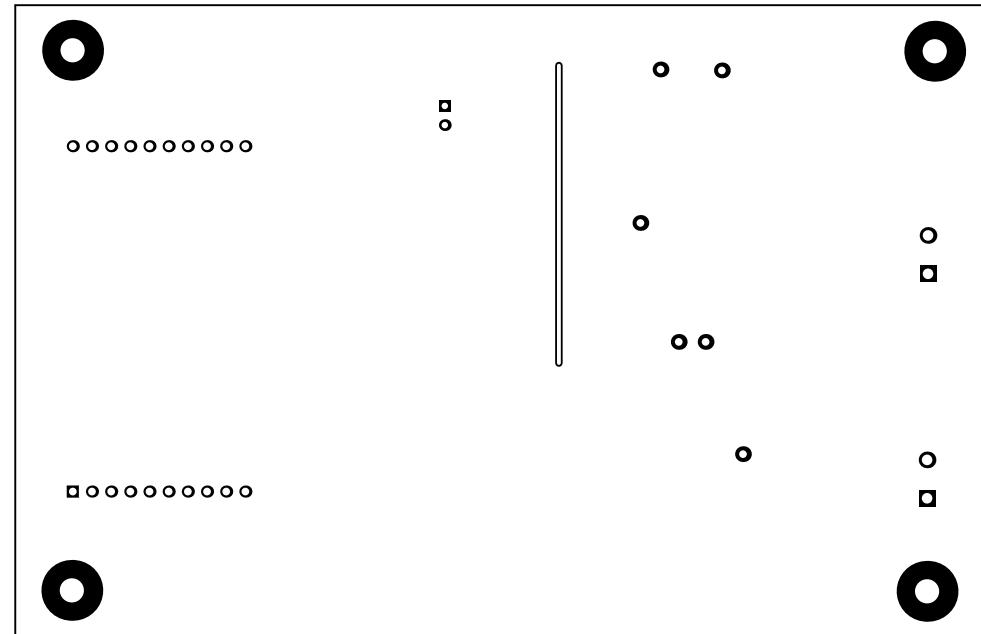
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01590	REV: R1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01590		
PLOT NAME = Top Solder Mask	GENERATED : 10/2/2017 2:27:06 PM	TEXAS INSTRUMENTS	



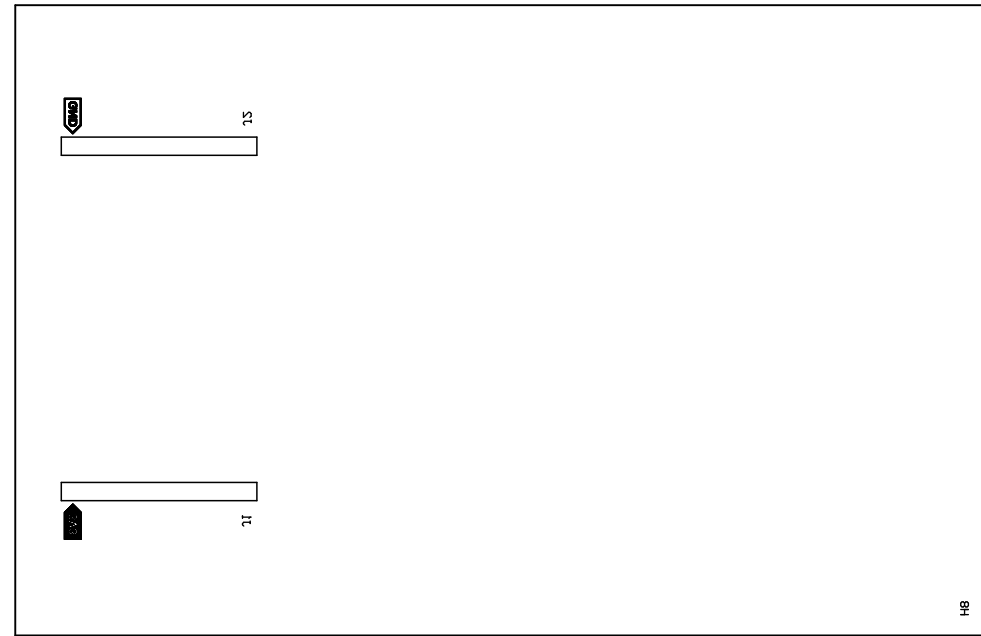
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01590	REV: R1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-01590		
PLOT NAME = Top Layer	GENERATED : 10/2/2017 2:27:08 PM	TEXAS INSTRUMENTS	



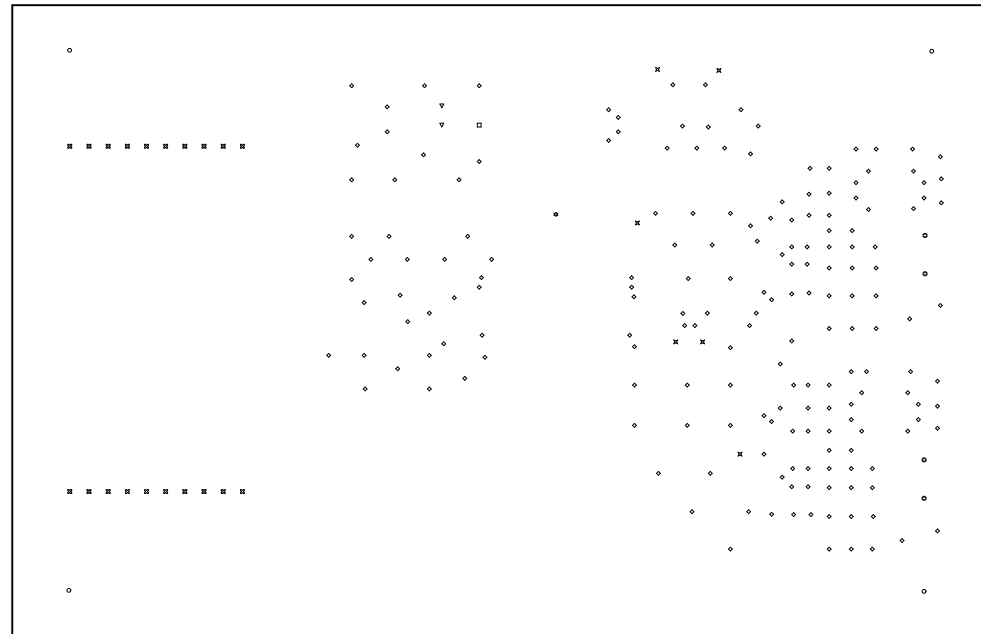
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01590	REV: R1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-01590		
PLOT NAME = Bottom Layer	GENERATED : 10/2/2017 2:27:10 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01590	REV: R1	SVN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01590		
PLOT NAME = Bottom Solder Mask	GENERATED : 10/2/2017 2:27:11 PM	TEXAS INSTRUMENTS	



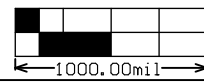
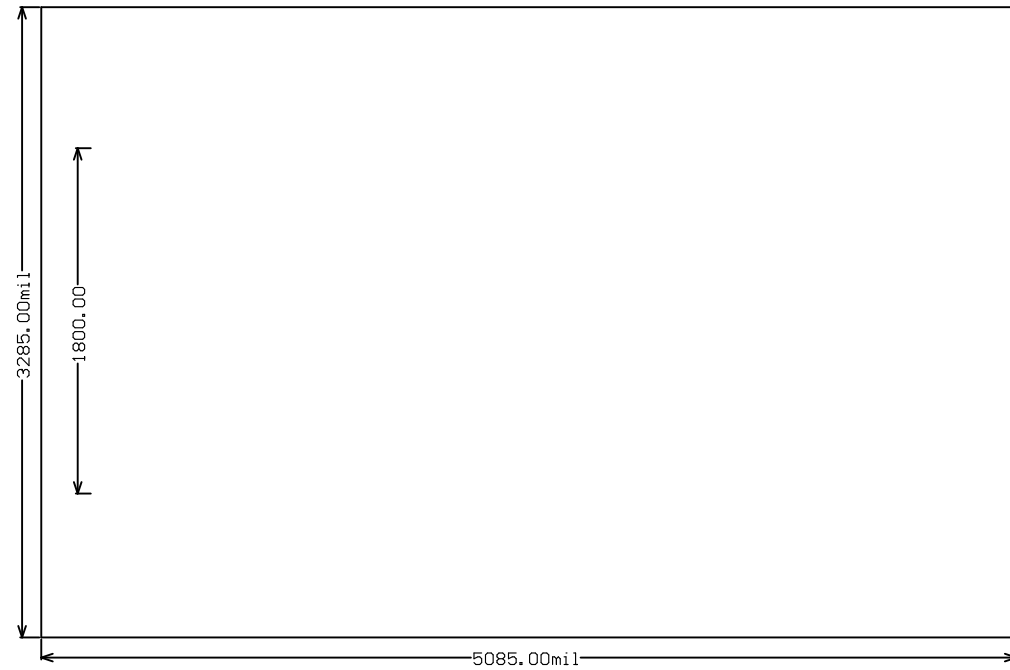
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01590	REV: R1	SVN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-01590		
PLOT NAME = Bottom Overlay	GENERATED : 10/2/2017 2:27:13 PM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
◇	182	16.00mil (0.406mm)	PTH	Round	Top Layer - Bottom Layer	
□	1	20.00mil (0.508mm)	PTH	Round	Top Layer - Bottom Layer	
▽	2	33.47mil (0.850mm)	PTH	Round	Top Layer - Bottom Layer	
⊠	6	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	20	40.16mil (1.020mm)	PTH	Round	Top Layer - Bottom Layer	
⊙	4	55.12mil (1.400mm)	PTH	Round	Top Layer - Bottom Layer	
○	4	125.98mil (3.200mm)	PTH	Round	Top Layer - Bottom Layer	
⊛	1	20.00mil (0.508mm)	NPTH	Slot	Top Layer - Bottom Layer	
220 Total						

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01590	REV: R1	SUN REV: Not In UersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01590		
PLOT NAME = Drill Drawing	GENERATED : 10/2/2017 2:27:15 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01590	REV: R1	SVN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-01590		
PLOT NAME = Board Dimensions	GENERATED : 10/2/2017 2:27:17 PM	TEXAS INSTRUMENTS	

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